Kulicke & Soffa Introduces New Vertical Wire Solutions to Expand Market Leadership

Elevating Memory Density with ATPremier MEM PLUS™

SINGAPORE, March 25, 2025 /PRNewswire/ -- Kulicke and Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S", "we" or the "Company") announced the launch of ATPremier MEM PLUS, serving high-volume memory applications.

The innovative ATPremier MEM PLUS *™* is a cutting-edge wafer level packaging solution, deploying innovative vertical wire technology to address emerging advanced memory applications within today's fast-paced semiconductor market. Engineered for high-volume, *at-the-edge* AI applications, K&S' vertical wire technology has broken barriers to enable a new level of transistor-dense DRAM and NAND assembly.

The Company anticipates advanced process capabilities, such as *ProVertical* and *ProCascade Loop,* to enable emerging memory applications as well as high-density applications in high-volume semiconductor markets outside of the memory market.

At-the-edge AI applications are demanding unprecedented advancements in memory technology and are anticipated to grow above a 25% compound annual growth rate over the coming five years. Larger capacities, higher performance, greater power efficiency, and more compact formfactor are increasingly essential, given that the historic approach of driving package density through transistor shrink continues to be prohibitively expensive for most high-volume semiconductor applications.

This ongoing dynamic has created the need for increasingly complex advanced semiconductor packaging solutions, and K&S' ATPremier MEM PLUS™ vertical wire solution and APTURA™ Fluxless Thermo-Compression (FTC) solution are both extremely well positioned to directly support future *at-the-edge* AI, memory and high computing needs.

The ATPremier platform is built to support advanced assembly requirements and provides an alternative to traditional copper pillar technology by removing the limitations of two-dimensional packaging. With capabilities to support next-generation memory devices, including in consumer mobile, this novel technology is enabling high-density advanced packaging without compromise. ATPremier reduces complexity, costs, and addresses the increasingly advanced needs of the high-volume semiconductor market.

ATPremier MEM PLUS™ delivers cutting-edge, memory-specific wafer-level packaging capabilities, empowering customers to stay ahead in the intensely competitive memory landscape. Key features include:

- **Response Based Processes**
  Technologies which are proprietary to K&S, including *ProVertical* and *ProCascade Loop*, would meet the precision wire bonding requirements of vertical and cascade wire interconnects, thereby ensuring optimal performance for memory applications.
- **Advanced Optical System and Inspection Features**

Equipped with state-of-the-art optical systems and yield-enhancing inspection tools, safeguarding product quality at every stage.

- **Factory Automation Integration**
  With the capability to integrate Auto Wafer Handlers or EFEM systems, ATPremier MEM PLUS supports seamless factory automation, improving efficiency and throughput in high-volume environments.

"By addressing critical challenges in Memory capability, the ATPremier MEM PLUS™ technology demonstrates a leap forward in efficiency and performance, offering our customers new opportunities to enhance the speed, capacity, and energy efficiency of memory products. This vision extends far beyond its initial use in DRAM. With inherent flexibility and scalability, the solution is positioned to deliver significant impact across broader IC applications, marking a future of high-performance devices at optimized costs," said Ivy Qin, Kulicke & Soffa's Vice President and General Manager of Ball Bonding.

Asterion®- PW – another revolutionary K&S solution for Power Semiconductor Applications

K&S has separately announced the concurrent launch of Asterion®-PW, extending its leadership in power device applications with a fast and precise ultrasonic pin welding solution. This advanced solution sets a new standard for pin interconnect capability – redefining efficiency, precision, and reliability.

Visit K&S at SEMICON China 2025

Together with K&S' broad portfolio of solutions, the ***ATPremier MEM PLUS™*** **and** ***Asterion®- PW*** will debut at the SEMICON China Trade Show in Shanghai, from March 26 through March 28, 2025, at Hall N3 Booth #3431.

About Kulicke & Soffa

Founded in 1951, Kulicke and Soffa Industries, Inc. specializes in developing cutting-edge semiconductor and electronics assembly solutions enabling a smarter and more sustainable future. Our ever-growing range of products and services supports growth and facilitates technology transitions across large-scale markets, such as advanced display, automotive, communications, compute, consumer, data storage, energy storage and industrial.

Contacts

Kulicke & Soffa
Marilyn Sim
Public Relations
+65-6880 9309
msim@kns.com

Kulicke & Soffa
Joseph Elgindy
Investor Relations
+1-215-784-7500
investor@kns.com

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